

**New Claims**

16. (New Claim) The printed wiring board as in claim 1, wherein the first metal is tin and the second metal is silver.

17. (new Claim) A printed wiring board comprising:

an insulator board having a via-hole;

a pair of conductor patterns, which include a metal and are formed on the insulator board;

a unified conductive compound, which includes a first metal and a second metal that has a higher melting point than a heating temperature required for interconnecting the conductor patterns; and

a pair of solid phase diffusion layers, which are formed by mutual solid phase diffusion between the same metal as the metal included in the conductor patterns and the same metal as the first metal included in the conductive compound, wherein the conductor patterns are electrically interconnected by the unified conductive compound and the solid phase diffusion layers.

18. (New Claim) The printed wiring board as in claim 17, wherein the conductive compound is an alloy that includes sintered metals made from metal particles.

19. (New Claim) The printed wiring board as in claim 17, wherein the metal is tin and the second metal is silver.

20. (New Claim) A printed wiring board comprising:

an insulator board having a via-hole;

a pair of conductor patterns, which include a metal and are formed on the insulator board; and

a unified conductive compound, which includes a first metal and a second metal that has a higher melting point than a heating temperature required for interconnecting the conductor pattern, wherein:

the conductive compound is an alloy that includes sintered metals made from metal particles including the first metal and other metal particles including the second metal; and

the conductor patterns are electrically interconnected by the unified conductive compound.

21. (New Claim) The printed wiring board as in claim 20, wherein the first metal is tin and the second metal is silver.

22. (New Claim) The printed wiring board as in claim 20, wherein in a sidewall of the unified conductive compound in the via-hole has a shape such that the farther from the conductor patterns on the sidewall, the closer the sidewall is to a center axis of the via-hole.

23. (New Claim) The printed wiring board of claim 1 wherein the shape of the sidewall of the unified conductive compound follows a protrusion of the insulator board that increases toward the center axis with increasing distance from the conductor patterns along the sidewall.

24. (New Claim) The printed wiring board of claim 1 wherein the sidewall of the unified conductive pattern is inclined with respect to the conductor patterns, wherein stress concentrations are avoided at an area of an electrical contact between the conductive patterns and the unified conductive compound.